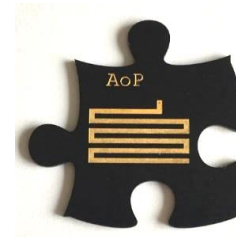


AMP – Active Mold Packaging

Value adding solution for advanced IC packages

Equipment Overview

Convert the Epoxy Mold Compound into an active carrier of functionality.



Active Mold Packaging Turnkey Solution Overview

LPKF provides a turnkey solution for the Active Mold Packaging process, consisting of the following items.

- Handler station for automatic on- & offloading of strips from magazines in and out of the laser station
- laser station for high-speed laser processing
- dust extraction unit
- process vacuum unit



product appearance subject to change, picture shows optional equipment

Automatic strip magazine handler for uninterrupted operation

- high-durable and force programmable rollers or push & pull option for on- & off-loader handler
- short change-over time between different magazine/ strip sizes
- uninterrupted operation with up to 4 magazines per loader
- good strip / bad strip sorting
- strip jamming prevention
- strip presence sensor



product appearance subject to change, picture shows optional equipment

Active Mold Packaging Laser Station

CE conform laser station for high-speed surface structuring and via drilling of Mold Compounds including:

- auto-loading for up to 300 x 100 mm strips
- track- & trace capability
- any type fiducial detection
- 2D-code reader
- design specific vacuum chuck
- inbuilt optical inspection unit for post-laser inspection
- die-map compatibility for increase package level accuracy



product appearance subject to change, picture shows optional equipment

Turn-key equipment delivered with

- Warranty: 3-year premium warranty, including 2 maintenance visits p.a. free of charge
- Warranty extension program: annual extension for up to 10 years available
- Installation & Training: 2+8 working days
- Packing: included
- Delivery term: FCA (free carrier), DAP (delivery at place)
- Lead time: approx. 16 weeks



product appearance subject to change, picture shows optional equipment

Active Mold Packaging Services provided by LPKF

LPKF Headquarters provide Active Mold Packaging (AMP) outsource services.

- Cleaning: Strip cleaning before & after lasering & electro-less plating
- Lasering: Top and bottom side circuitry, via drilling & singulation
- Plating: Electroless plating copper, nickel, gold (beaker glass)
- Inspection: Microscope (visual), SEM, cross-section, roughness measurement
- Volume: Prototype builds and small volume manufacturing



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